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Patent Claims

1. A substrate (S; S1; S2; S3) having at least two metallized polymer studs (PS; PS1; PS2; PS3) for soldered connections to wiring (V) and having conductor runs (LZ) which lead away from the polymer studs (PS; PS1; PS2; PS3) on the lower face (U) of the substrate (S; S1; S2; S3), with the polymer studs (PS; PS1; PS2; PS3) having at least one step (ST; ST1, ST10; ST2; ST3) in order to form at least one projection (E; E1; E10; E2; E3).
2. The substrate (S) as claimed in claim, characterized by a cylindrical projection (E) which is arranged concentrically with respect to the polymer stud (PS).
3. The substrate (S) as claimed in claim 2, characterized in that the cylindrical projection (E) has a diameter (d) of between 100 μm and 300 μm , and a height (h) of between 25 μm and 250 μm .
4. The substrate (S1) as claimed in claim 1, characterized in that polymer studs (PS1) are provided, having two projections (E1; E10) and two steps (ST1; ST10).
5. The substrate (S2) as claimed in claim 1, characterized in that polymer studs (PS2) are provided, having a number of projections (E2) arranged at a distance from one another on a step (ST2).
6. The substrate (S3) as claimed in claim 1, characterized in that polymer studs (PS3) are provided, having annular projections (E3) arranged on a step (ST3).